Filler Material, And Pretreatment Of Printed Circuit Board Components To Facilita Application Of A Conformal EMI Shiel

Inventor(s): Lowell E Kolb et al

FIG. 1

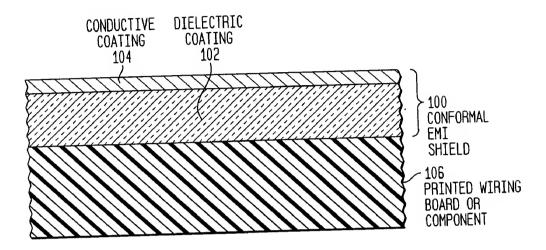
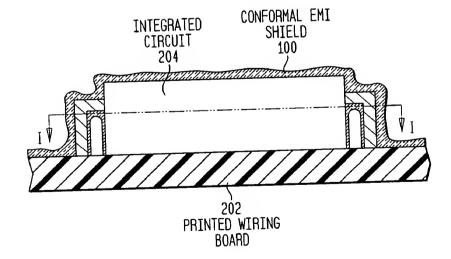


FIG. 2A

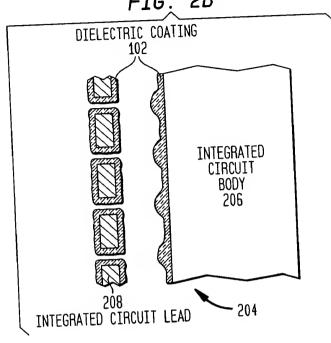


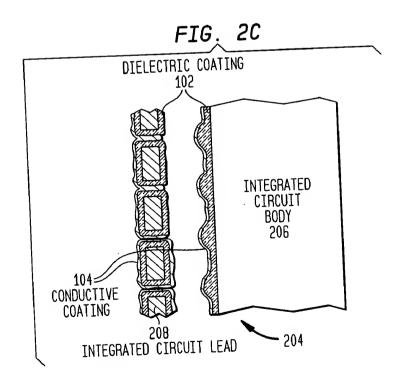
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FIG. 2B



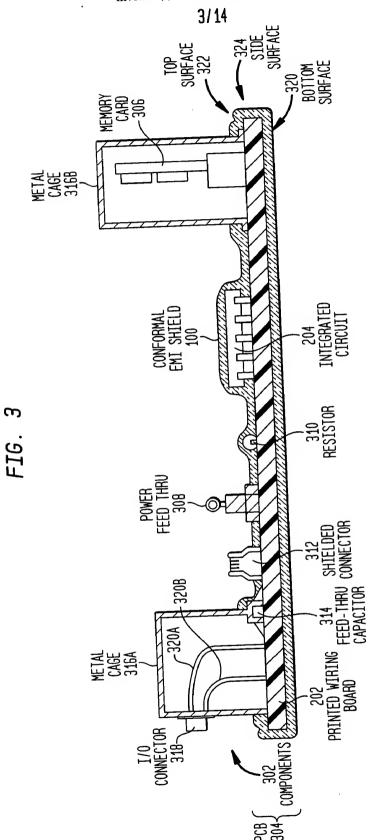


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Filler Material And Pretreatment Of Printed
Circuit Board Components To Facilitate
Application Of A Conformal EMI Shield



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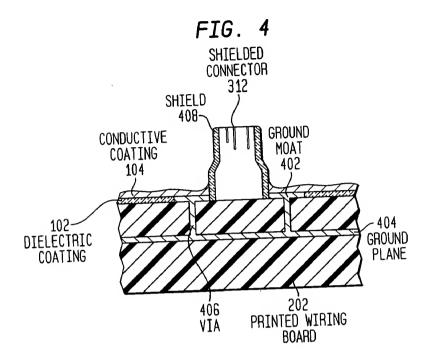
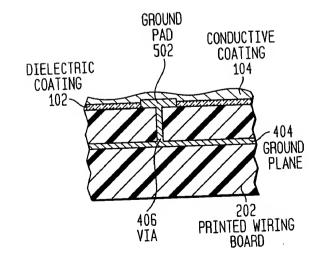


FIG. 5



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FIG. 6A

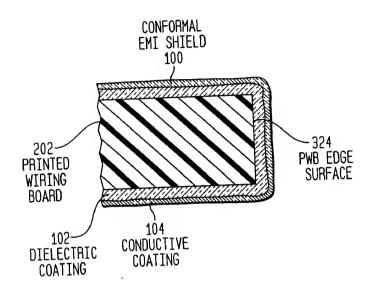


FIG. 6B

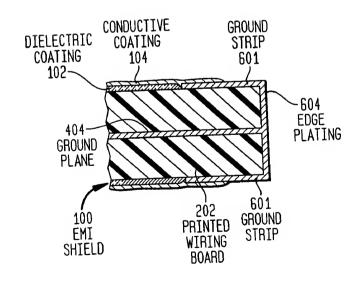


FIG. 6C

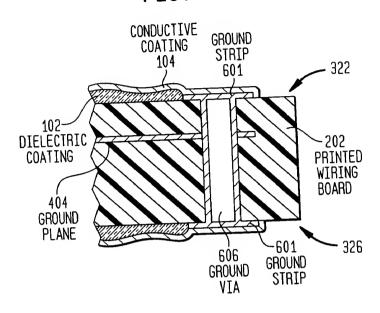
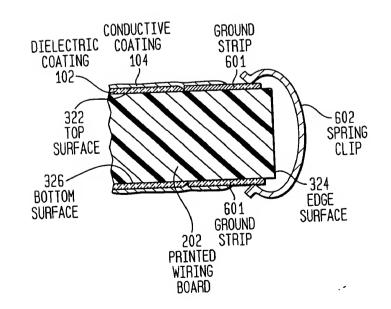


FIG. 6D



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FIG. 6E

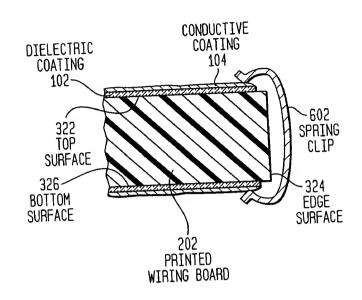
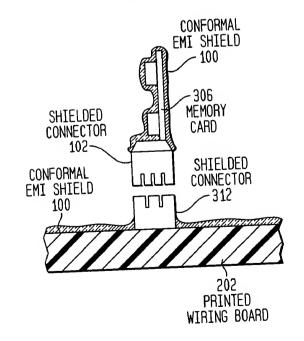


FIG. 7



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FIG. BA

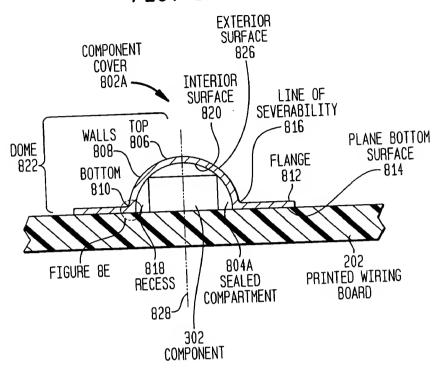
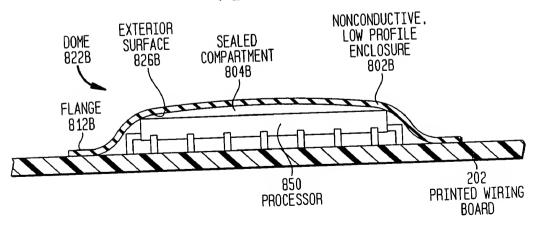


FIG. 8B

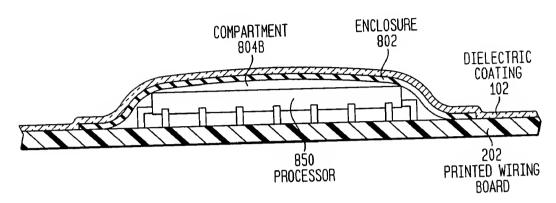


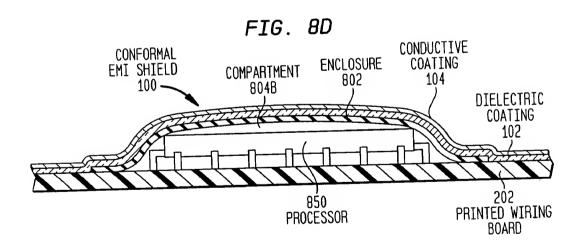
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FIG. BC





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FIG. 8E-1

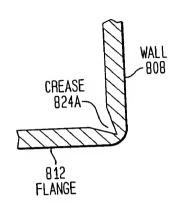
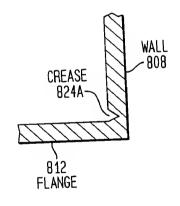


FIG. 8E-2



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FIG. 9A

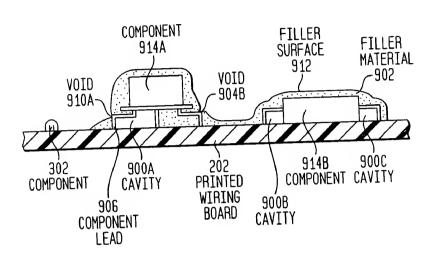
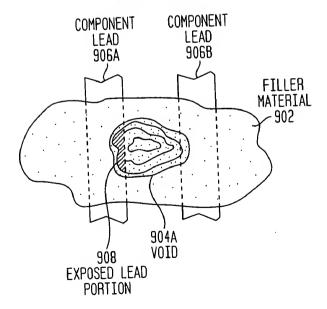


FIG. 9B



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FIG. 9C

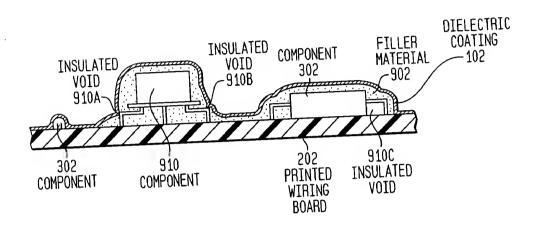
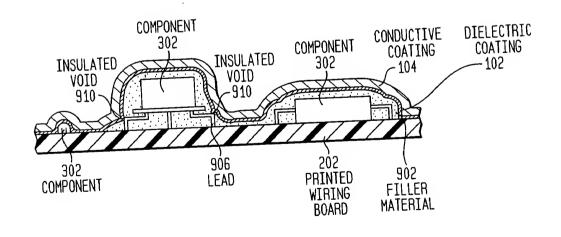
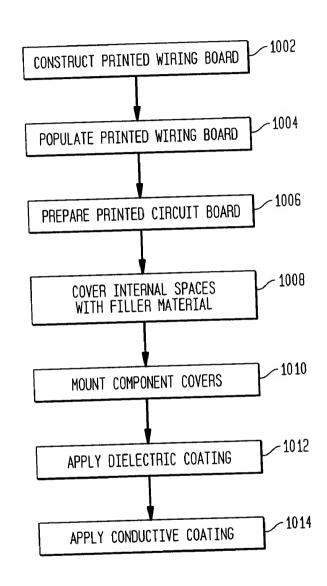


FIG. 9D



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FIG. 10



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FIG. 11

